SRM INSTITUTE OF SCIENCE & TECHNOLOGY
(Deemed to be University u/s 3 of UGC Act, 1956)

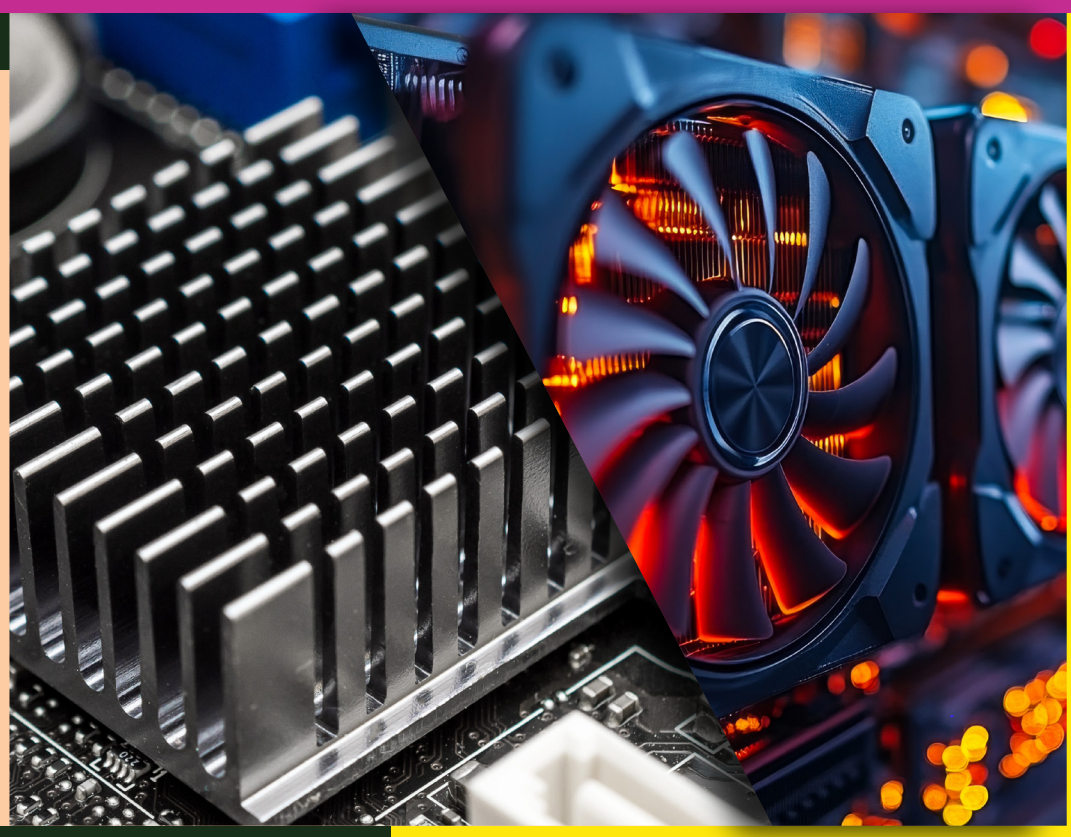
DELL intel

Capstone Program in

Electronic Cooling - Highlights

What is the Industry Internship Experience in Classroom (IIEC)

- Industry expert(s) teaches set of modules on a specific subject in the university/classroom environment.
- No interview process. All students can register. No Internship Fees for SRMIST – KTR students.
- Identical Modules are taught Gain Identical experience like an intern at the industry
- No Traditional Textbook method. All modules are practical relevant techniques imparting skills to survive in the industry.
- No Time away from campus
- Finish it in one Semester within the confines of the classroom Earn 6 Credits upon successful completion (Internal Evaluation)
- SRM is the FIRST and ONLY University in India to do IIEC
- Huge differentiating factor for students graduating and applying for higher studies or industry job.
- Industrial Ramp-up time is drastically cut-down. Hiring Managers prefer such candidates



Capstone Program Credit Distribution for Undergraduate Students

Year	Credits	Lectures	Lab Assignments	Final Exam	Project Work + Lab Report	Total	Subject Code	Semester	
								3rd year	Eighth Semester
Third Year	6 Credits (CPEC)	30%	40%	30%	NA	100%	CPEC	Lectures + Lab + Final Exam	NA
Fourt Year	15 Credits (CPEC-P)	Only Project in the Lab			Yes	100%	CPEC-P		Final Year Project (CPEC-P Code)

- Undergraduate Students cannot register for CPEC-P (Capstone project) without completing CPEC (Capstone lecture + lab component)
- All three components must be attended and completed (lectures + assignments + final exam) for evaluation of letter grade
- CPEC à Capstone Program in Electronic Cooling
- CPEC-P à Capstone Program in Electronic Cooling – Project

Co-Req/Pre-req can be taken concurrently with the Capstone (CPEC) program

- **Microelectronics Thermal Management OR Electronic Thermal Management (SRMIST-KTR)**

Capstone Program Credit Distribution for Graduate (M. Tech/ Doctoral) Students

Year	Credits	Lectures	Lab Assignments	Final Exam	Project Work + Lab Report	Total	Subject Code	Semester	
								First year	Fourth Semester
First Year	6 Credits (CPEC)	20%	50%	30%	NA	100%	CPEC	Lectures + Lab + Final Exam	NA
Second Year	20 Credits (CPEC-P)	Only Project in the Lab			Yes	100%	CPEC-P		Final Year Project (CPEC-P Code)

- Undergraduate Students cannot register for CPEC-P (Capstone project) without completing CPEC (Capstone lecture + lab component)
- All three components must be attended and completed (lectures + assignments + final exam) for evaluation of letter grade
- CPEC à Capstone Program in Electronic Cooling
- CPEC-P à Capstone Program in Electronic Cooling – Project

Co-Req/Pre-req can be taken concurrently with the Capstone (CPEC) program

Microelectronics Thermal Management OR Electronic Thermal Management (SRMIST)

Capstone in Electronic Cooling

Course	Capstone Program	SRMIST-KTR Credits
Prerequisite/Core quisite	Electronics Thermal Management (ETM) for non Mechanical Engineering, Microelectronics Thermal Management (MTM) for Mechanical Engineering	3 Credits
Core Course	Capstone Program in Electronic Cooling (CPEC)	6 Credits
Capstone Project	Capstone Program in Electronic Cooling – Project (CPEC-P)	15 Credits

Computer Science Students

- Hardware Companies hire a lot of computer science students and use their skills
- Algorithm Cooling in smartphones, smart watches and other thin form factor devices.
- Coolant Distribution Units in Data Centers – Control algorithms to cool.
- Software as a new means of cooling devices
- AI/ML and coding is exploited heavily in companies such as Apple and Google and other smartphone manufacturers and device companies
- Capstone program will teach students these latest cooling methods required to succeed in the industry

Future Prospects & Jobs in the Industry

Masters and Doctoral Programs in US/Europe

- 1:1 Masters Program (First year in SRM and Second year in select US Universities)

Industry jobs

- Thermal Engineers
- Thermal Architects
- Packaging Engineers
- Manufacturing Engineers
- Mechanical Engineer
- Silicon Packaging Architect
- Data Center Architects
- AI/ML Silicon Architects

NAAC A++ | MHRD Govt. of India, UGC University Grants Commission: Category 1 with 12B Status | nirf National Institutional Ranking Framework: (2024) 12th Ranked University | QS: (2025) World Ranking one among 46 Indian Universities | THE Times Higher Education World University Rankings: (2024) World Ranking one among 91 Indian Universities | QS 4 Star Rating: VERY GOOD QS 4 Star Rated Globally | ShanghaiRanking: (2024) World Ranking Ranked 5-7 in Indian Universities